



SGM3784

Dual 1.1A LED Flash Driver with I²C-Compatible Interface

GENERAL DESCRIPTION

The SGM3784 is a very compact, highly efficient, dual white LED flash driver for high resolution camera phones that improves picture and video quality in low light environments. The device integrates a programmable 1.6MHz or 3MHz synchronous inductive boost converter, an I²C-compatible interface, and two 1.1A current sources. The high switching frequency enables the use of a tiny, 1mm high, low cost, 1μH power inductor, and the parallel current sources permit LED cathode grounding for thermally enhanced, low EMI and compact layouts.

The LED driver maximizes efficiency over the entire battery voltage range to maximize the input-power-to-LED-power conversion and minimize battery current draw during flash events.

A programmable DC battery current limit safely maximizes LED current for all LED forward voltage and battery voltage conditions.

A Transmitter Mask (TxMASK) input enables fast reduction of the flash LED currents and battery current during a power amplifier current burst. The I²C-compatible interface can be used to program timers and currents and to read back status bits for operation monitoring and safety control.

The SGM3784 is available in WLCSP-2×1.6-12B package and operates within specification over the full -40°C to +85°C operating temperature range.

FEATURES

- **Ultra Compact Solution**
 - ◆ Small, WLCSP-2×1.6-12B Package
 - ◆ Smallest Footprint, 1mm-Height, 1μH Power Inductor
- **LED Current Source for Local LED Grounding**
 - ◆ Simplified Routing to and from LEDs
 - ◆ Improved LED Thermal Dissipation
- **Synchronous 3MHz PWM Boost Converter, No External Diode**
- **High Efficiency: 95% Peak**
- **I²C Programmable**
 - ◆ Currents up to 1.1A in Flash Mode per LED When V_{IN} is not Lower than 3.6V (The Total 2 LEDs Current is 1.5A When V_{IN} is Lower than 3.6V)
 - ◆ Torch Mode
 - ◆ Programmable DC Battery Current Limit
 - ◆ Programmable Flash Timer up to 1600ms
 - ◆ Low Battery Mode to Reduce LED Current Automatically
- **Device Control**
 - ◆ I²C-Compatible Control Registers
 - ◆ External STROBE and Torch Input Pins
 - ◆ Transmitter Mask (TxMASK) Input
- **Safety Features**
 - ◆ Thermal Overload Protection
 - ◆ Inductor Fault Detection
 - ◆ LED Short-Circuit/Open-Circuit Protection

APPLICATIONS

Camera-Enabled Cellular Phones and Smart-Phones
Digital Still Cameras, Camcorders and PDAs

PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM3784	WLCSP-2x1.6-12B	-40°C to +85°C	SGM3784YG/TR	XXXXX 3784YG	Tape and Reel, 3000

NOTE: XXXXXX = Date Code and Vendor Code.

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

VIN, SDA, SCL, EN, GPIO, STROBE,
 LED1, LED2, SW, VOUT to PGND -0.3V to 6V
 PGND to SGND -0.3V to 0.3V
 Junction Temperature +150°C
 Storage Temperature Range.....-65°C to +150°C
 Lead Temperature (Soldering 10 sec).....+260°C
 ESD Susceptibility
 HBM..... 4000V
 MM..... 400V
 CDM 1000V

RECOMMENDED OPERATING CONDITIONS

Supply Voltage Range2.7V to 5V
 Junction Temperature Range.....-40°C to +125°C
 Operating Temperature Range-40°C to +85°C

OVERSTRESS CAUTION

Stresses beyond those listed may cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational section of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

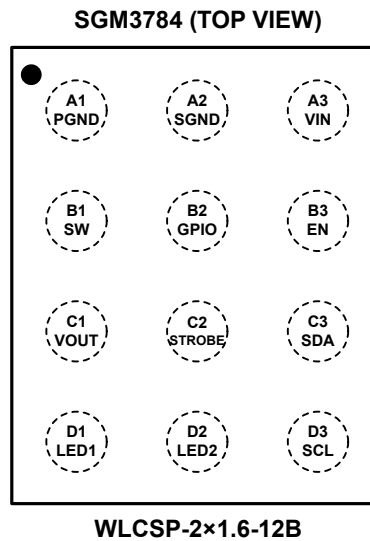
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time.

PIN CONFIGURATION



PIN DESCRIPTION

PIN	NAME	FUNCTION
A1	PGND	Power Ground.
A2	SGND	Signal Ground.
A3	VIN	Input Voltage for the Device. Connect an input bypass capacitor very close to this pin.
B1	SW	Boost Switch. Connect the power inductor between SW and the input capacitor.
B2	GPIO	This pin enables the part to function in torch mode or functions as a Transmitter Mask (TxMASK) input, depending on the value set using Bits[5:4] in Register 0x02 (see Table 8). When this pin is configured as a TxMASK input, the flash current is reduced to the TxMASK current programmed in Register 0x07 (for LED1) and Register 0x0A (for LED2).
B3	EN	Enable. Registers are set to their default values when EN is brought from low to high.
C1	VOUT	Boost Output. Connect an output bypass capacitor very close to this pin. This pin is the output for the 5V external voltage mode.
C2	STROBE	Strobe Signal Input. This pin synchronizes the flash pulse to the image capture. In most cases, this signal comes directly from the image sensor.
C3	SDA	I ² C Data Signal.
D1	LED1	Current Source for LED1. Connect this pin to the anode of flash LED1.
D2	LED2	Current Source for LED2. Connect this pin to the anode of flash LED2.
D3	SCL	I ² C Clock Signal.

ELECTRICAL CHARACTERISTICS(V_{IN} = 3.6V, typical values are at T_A = 25°C, unless otherwise noted.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
SUPPLY					
Input Voltage Range		2.7		5	V
Under-Voltage Lockout Threshold	V _{IN} falling		2.3	2.45	V
Under-Voltage Lockout Hysteresis			150		mV
Shutdown Current	Current into V _{IN} pin, V _{IN} = 2.7V to 4.5V, EN = 0V		0.2	1	μA
Standby Current	Current into V _{IN} pin, V _{IN} = 2.7V to 4.5V, EN = 1.8V		5	7.5	μA
Operating Quiescent Current	Torch mode, I _{LED} = 100mA		220	370	μA
SW Switch Leakage Current	V _{SW} = 5V		0.2	1	μA
LED DRIVER					
Assist Light, Torch Mode LED Current per Channel	Assist light value setting = 0 (0 0000 binary)		0		mA
	Assist light value setting = 16 (1 0000 binary)		300		mA
Flash Mode LED Current per Channel	Flash value setting = 0 (00 0000 binary)		0		mA
	Flash value setting = 60 (11 1100 binary)		1.1		A
LED Current Accuracy per Channel	Flash code = 0x3C, for nominal 1122mA	84	97	110	%
	Flash code = 0x24, for nominal 474.7mA	86	99	112	
	Flash code = 0x14, for nominal 374.3mA	86.5	100	113.5	
	Torch code = 0x08, for nominal 150.3mA	86	101	116	
	Torch code = 0x01, for nominal 18.7mA		105		
LED Channel Mismatch	Flash code = 0x3C, for nominal 1122mA		5.2	9.1	%
	Flash code = 0x24, for nominal 474.7mA		4.9	9.0	
	Flash code = 0x14, for nominal 374.3mA		4.9	9.0	
	Torch code = 0x08, for nominal 150.3mA		4.9	9.0	
	Torch code = 0x01, for nominal 18.7mA		3.8		
SWITCHING REGULATOR					
Switching Frequency	Switching frequency = 3MHz	2.7	3	3.3	MHz
	Switching frequency = 1.6MHz	1.4	1.6	1.8	
N-FET Resistance			100		mΩ
P-FET Resistance			100		mΩ
Voltage Output Mode					
V _{OUT} Voltage			5		V
Line Regulation	I _{LOAD} at V _{OUT} pin = 300mA		0.3		%/V
Load Regulation			0.7		%/A
Pass-Through Mode Transition					
Flash Mode					
V _{IN} to LED1/LED2, Entry	I _{LED1} = I _{LED2} = 1.1A		580		mV
V _{IN} to LED1/LED2, Exit	I _{LED1} = I _{LED2} = 1.1A		435		mV
Torch Mode					
V _{IN} to LED1/LED2, Entry	I _{LED} = 300mA		380		mV
V _{IN} to LED1/LED2, Exit	I _{LED} = 300mA		285		mV
SAFETY FEATURES					
Maximum Timeout for Flash		1450	1600	1780	ms
DC Current Limit	DC current value setting = 0 (000 binary)		1.0		A
	DC current value setting = 1 (001 binary)		1.25		
	DC current value setting = 2 (010 binary)		1.5		
	DC current value setting = 3 (011 binary)		1.75		
	DC current value setting = 4 (100 binary)		2.0		
	DC current value setting = 5 (101 binary)		2.25		
	DC current value setting = 6 (110 binary)		2.5		
DC current value setting = 7 (111 binary)		2.75			

ELECTRICAL CHARACTERISTICS (continued)

(V_{IN} = 3.6V, typical values are at T_A = 25°C, unless otherwise noted.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
DIGITAL INPUTS/GPIO PIN					
Input Logic Low Voltage				0.4	V
Input Logic High Voltage		1.5			V
GPIO, STROBE Pull-Down Resistance		250	390	550	kΩ
Torch Glitch Filtering Delay	From GPIO (Torch) rising edge to device start		10		ms
Low Battery Mode Transition Voltage					
Hysteresis			50		mV
Coil Peak Current Limit			2.85		A
Over-Voltage Detection Threshold			5.3		V
LED1/LED2 Short-Circuit Detection Comparator Reference Voltage			0.6		V
Thermal Shutdown Threshold					
Thermal Shutdown Rising Threshold			150		°C
Thermal Shutdown Falling Threshold			140		°C

I²C-COMPATIBLE INTERFACE TIMING SPECIFICATIONS ⁽¹⁾

DESCRIPTIONS	PARAMETER	MIN	MAX	UNITS
SCL Clock Frequency	f _{SCL}		1000	kHz
SCL High Time	t _{HIGH}	0.26		μs
SCL Low Time	t _{LOW}	0.5		μs
Data Setup Time	t _{SU, DAT}	50		ns
Data Hold Time	t _{HD, DAT}	0	0.9	μs
Setup Time for Repeated Start	t _{SU, STA}	0.26		μs
Hold Time for Start/Repeated Start	t _{HD, STA}	0.26		μs
Bus Free Time between a Stop and a Start Condition	t _{BUF}	0.5		μs
Setup Time for Stop Condition	t _{SU, STO}	0.26	120	μs
Rise Time of SCL and SDA	t _R	20 + 0.1C _B ⁽²⁾	120	ns
Fall Time of SCL and SDA	t _F	20 + 0.1C _B ⁽²⁾	50	ns
Pulse Width of Suppressed Spike	t _{SP}	0	400	ns

NOTES:

- Guaranteed by design.
- C_B is the total capacitance of one bus line in picofarads.

TIMING DIAGRAM

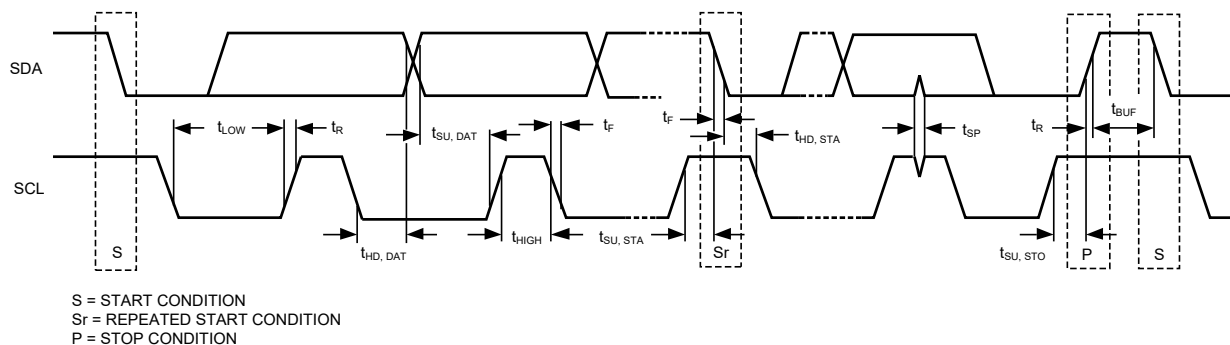
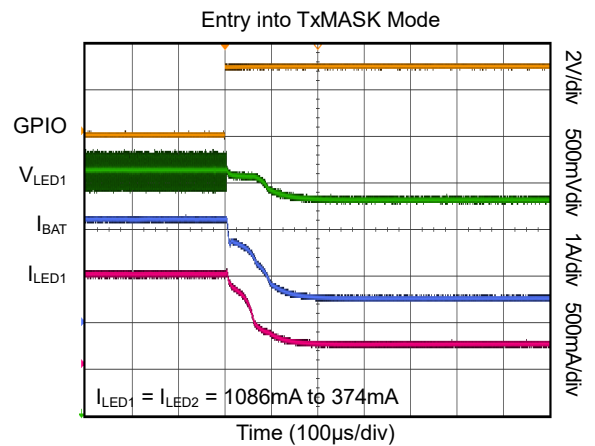
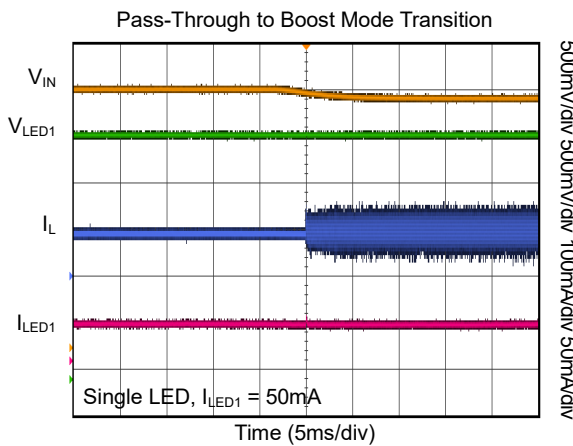
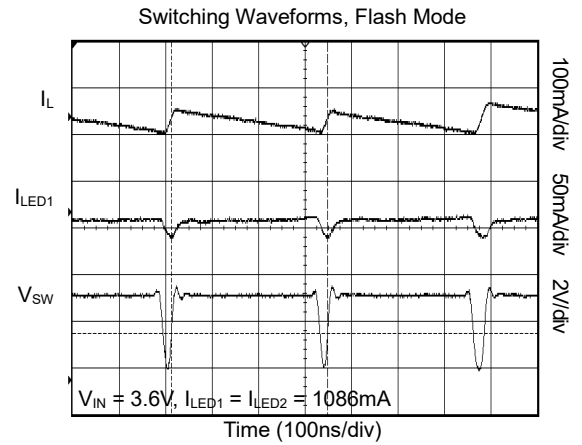
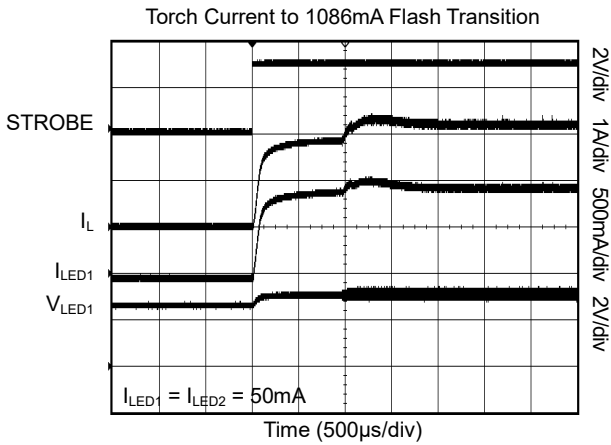
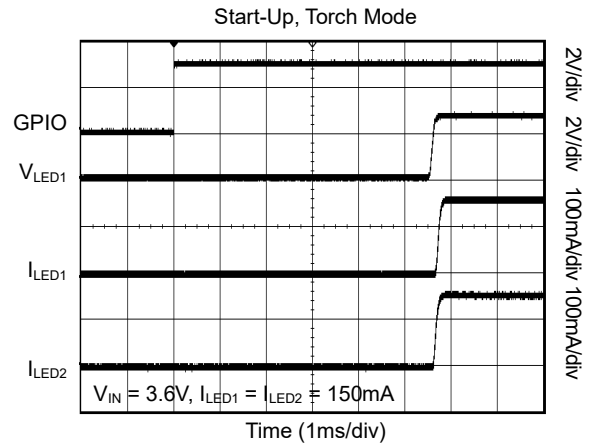
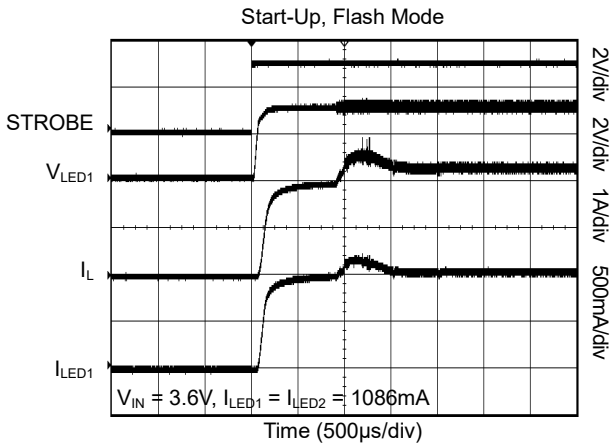


Figure 1. I²C-Compatible Interface Timing Diagram

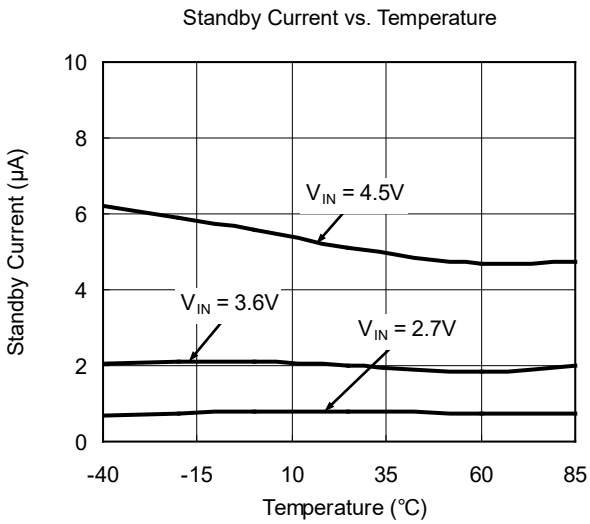
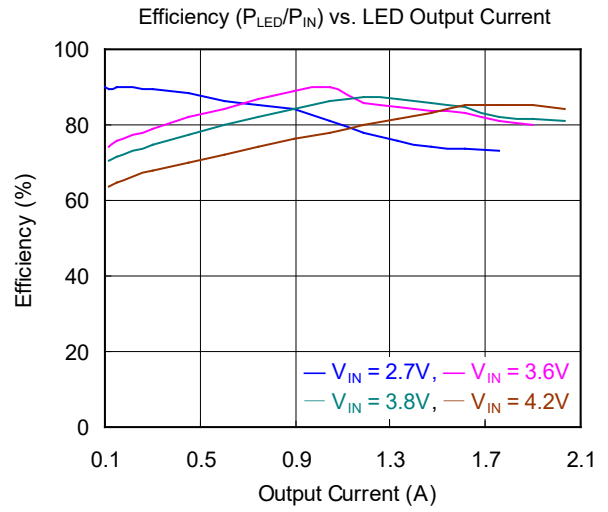
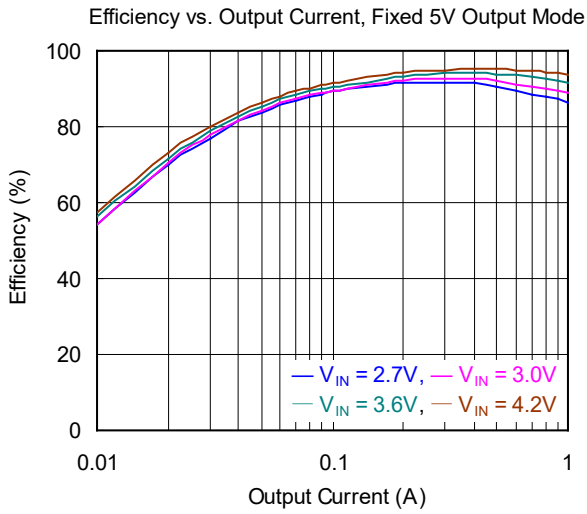
TYPICAL PERFORMANCE CHARACTERISTICS

T_A = +25°C, L = 1μH, C_{IN} = 10μF, C_{OUT} = 10μF, unless otherwise noted.



TYPICAL PERFORMANCE CHARACTERISTICS (continued)

T_A = +25°C, L = 1μH, C_{IN} = 10μF, C_{OUT} = 10μF, unless otherwise noted.



FUNCTIONAL BLOCK DIAGRAM

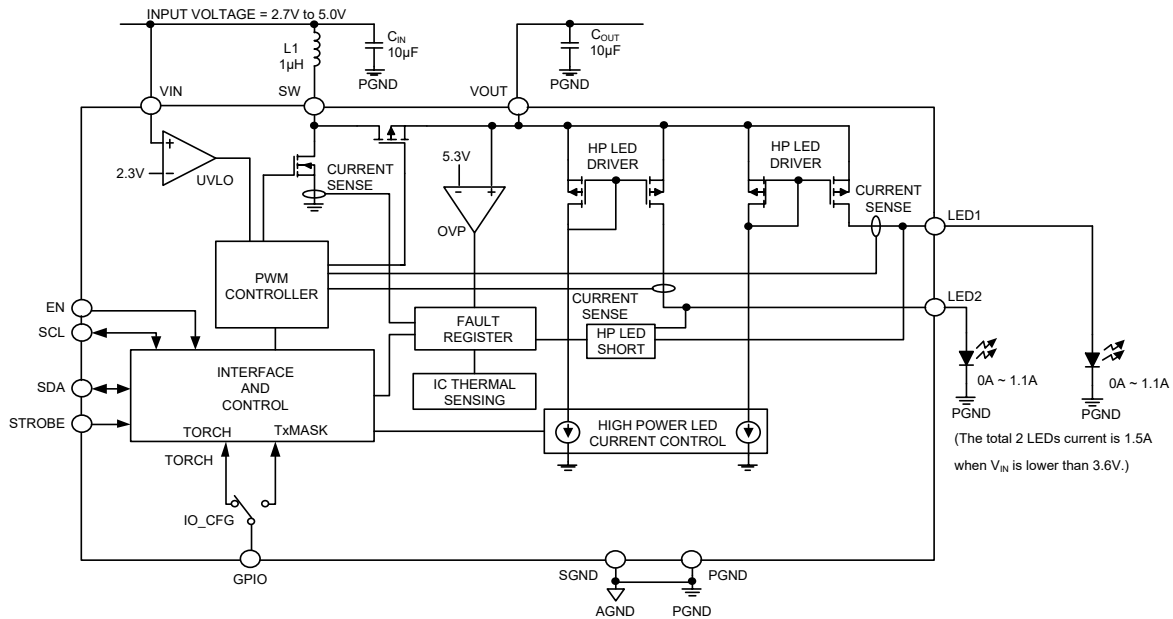


Figure 2. Detailed Block Diagram

THEORY OF OPERATION

The SGM3784 is a high power, I²C programmable, dual white LED driver ideal for driving white LEDs for use as a camera flash. The SGM3784 includes a boost converter and two current regulators suitable for powering two high power white LEDs.

White LED Driver

The SGM3784 drives a synchronous 3MHz boost converter as required to power the high power LEDs.

- If the sum of the LED forward voltage plus the current source headroom voltage is higher than the battery voltage, the boost converter is turned on.
- If the battery voltage is higher than the sum of the LED forward voltage plus 2× the current source headroom voltage, the boost converter is disabled and the part operates in pass-through mode.

The SGM3784 uses an integrated P-FET high-side current regulator for accurate brightness controls.

The SGM3784 supports the setting of different currents for each LED, although this configuration is not recommended. Any mismatch in the forward voltage of the two LEDs translates directly to lower efficiency, as well as lower accuracy of the current for the lower voltage LED. It is recommended that the voltages on

the two LEDs be kept within 1V of one another during operation. The user can disable one LED and use the other LED only, if desired.

Modes of Operation

When the EN pin is high, the I²C-compatible interface can be used to set the SGM3784 to one of seven modes of operation. These modes are configured using the LED_MOD bits (Bits[2:0]) in Register 0x01 (see Table 1).

Table 1. Modes of Operation Set by the LED_MOD Bits

LED_MOD BITS	OPERATING MODE
000	Standby mode, consuming 5µA typical (default).
001	Fixed 5V output mode.
010	Assist light mode with continuous LED current.
011	Flash mode with LED currents up to 1.1A available for up to 1.6sec.
100	Independent trigger mode with timeout enabled. (LED outputs are disabled if they are on longer than the timer value configured by the FL_TIM bits)
101	Independent trigger mode with timeout disabled. (FL_TIM value is ignored)
110	Fixed 5V output mode with torch mode. (total output current must be below 500mA)
111	Reserved.

THEORY OF OPERATION (continued)

Assist Light Mode

Assist light mode provides continuous LED current that is programmable from 0mA to 300mA. Set the assist light current using the I_TOR1 bits in Register 0x08 (for LED1) and the I_TOR2 bits in Register 0x0B (for LED2).

To enable assist light mode, set the LED_MOD bits to 010 in Register 0x01, and set the LED1_EN and/or LED2_EN bits to 1 in Register 0x0F. To disable assist light mode, set the LED_MOD bits to 000 (standby mode), or set the LED1_EN and LED2_EN bits to 0.

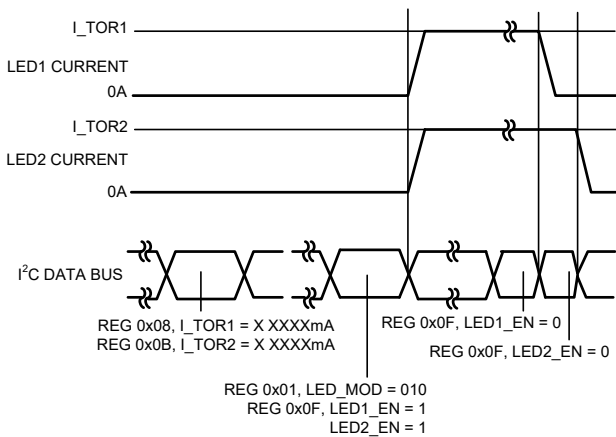


Figure 3. Enabling Assist Light Mode

Flash Mode

Flash mode provides up to 1.1A per LED for a programmable time of up to 1.6 seconds. Set the flash current using the I_FL1 bits in Register 0x06 (for LED1) and the I_FL2 bits in Register 0x09 (for LED2). Set the maximum flash duration using the FL_TIM bits (Bits[3:0]) in Register 0x02.

To enable flash mode, set the LED_MOD bits to 011 in Register 0x01, and set the LED1_EN and/or LED2_EN bits to 1 in Register 0x0F. If the LED1_EN or LED2_EN bit is set to 0, the corresponding LED will not output current during the flash, regardless of the flash current level setting.

To enable flash mode without using the STROBE pin, set the STR_MOD bit to 0 in Register 0x01 (software strobe mode). When the STR_MOD bit is set to 1 (hardware strobe mode), setting the STROBE pin high enables flash and synchronizes it to the image sensor. Hardware strobe mode has two timeout modes: level sensitive and edge sensitive.

Level-Sensitive STROBE Mode

In level-sensitive mode, the duration of STROBE high sets the duration of the flash up to the maximum time set by the FL_TIM timeout bits in Register 0x02 (see Figure 4). If STROBE is kept high longer than the duration set by the FL_TIM bits, a timeout fault disables the flash. The FL_TO timeout fault flag (Bit 4) is set in the fault information register (Register 0x0C).

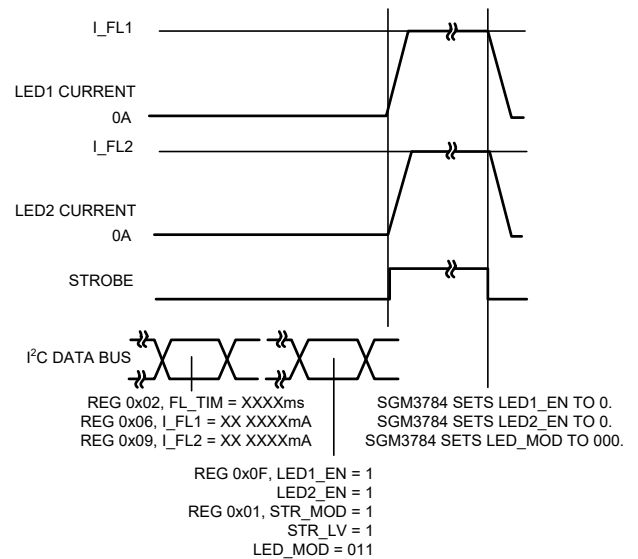


Figure 4. Flash Operation: Level-Sensitive Mode

Edge-Sensitive STROBE Mode

In edge-sensitive mode, a rising edge on the STROBE pin enables the flash, and the FL_TIM bits set the flash duration (see Figure 5).

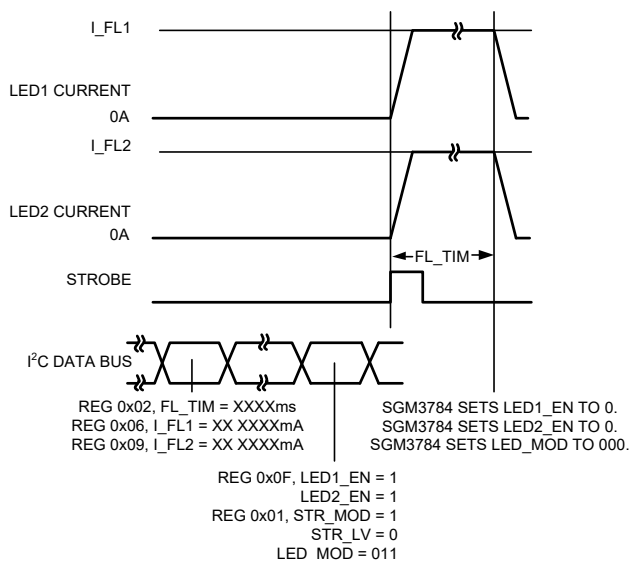


Figure 5. Flash Operation: Edge-Sensitive Mode

THEORY OF OPERATION (continued)

Assist to Flash Mode

The STR_POL bit in Register 0x01 can be used to change the default polarity of the STROBE pin from active high to active low. Additional image sensor-specific assist to flash enable modes are included in the device (see Figure 6).

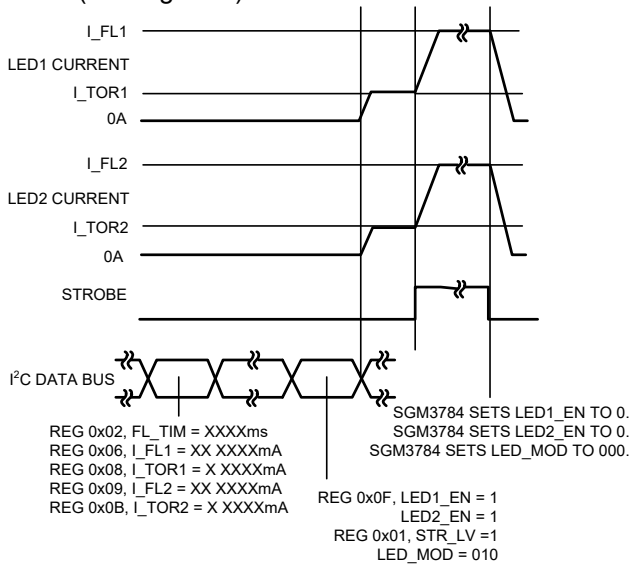


Figure 6. Enabling Assist to Flash (Level-Sensitive) Mode

Torch Mode

Set the assist/torch light current using the I_TORx bits. To enable torch mode, set the LED_MOD bits to 000 (standby mode), and set the LED1_EN and LED2_EN bits to 1 in Register 0x0F; then bring GPIO high. Disable the LED current by bringing GPIO low or by setting the LED1_EN and LED2_EN bits to 0. Bringing GPIO low during torch mode automatically sets LED1_EN and LED2_EN = 0. To reenale torch mode, set LED1_EN and LED2_EN = 1 and bring GPIO high again (see Figure 7).

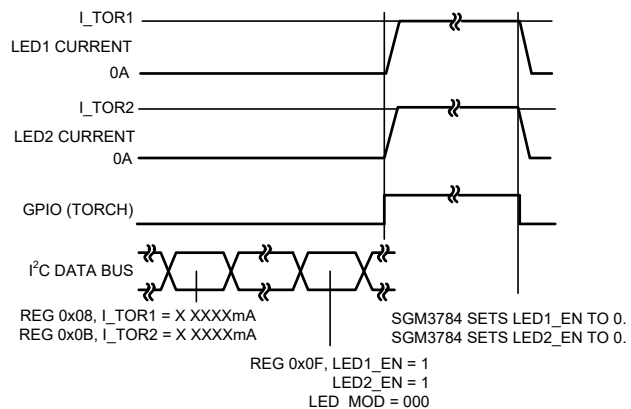


Figure 7. Enabling External Torch Mode Using the GPIO Pin

Torch to Flash Mode

The driver can move directly from external torch mode (using the GPIO pin) to flash mode by bringing the STROBE pin high before GPIO is brought low. Bringing the GPIO (torch) pin low before STROBE goes high prevents the flash from firing.

The SGM3784 returns to standby mode after a successful flash and sets the LED1_EN and LED2_EN bits to 0 in Register 0x0F.

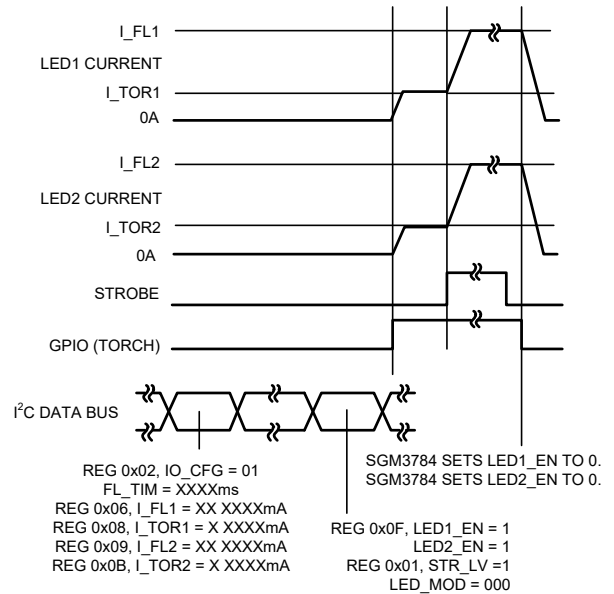


Figure 8. Enabling Flash Mode from External Torch Mode

THEORY OF OPERATION (continued)

TxMASK Operation

When the SGM3784 is in flash mode, the TxMASK function can reduce the battery load in response to the system enabling a power amplifier. The device remains in flash mode, but the LED driver output current is reduced to the programmed TxMASK current level in less than 21µs. The TxMASK current level is programmed in Register 0x07 (for LED1) and in Register 0x0A (for LED2).

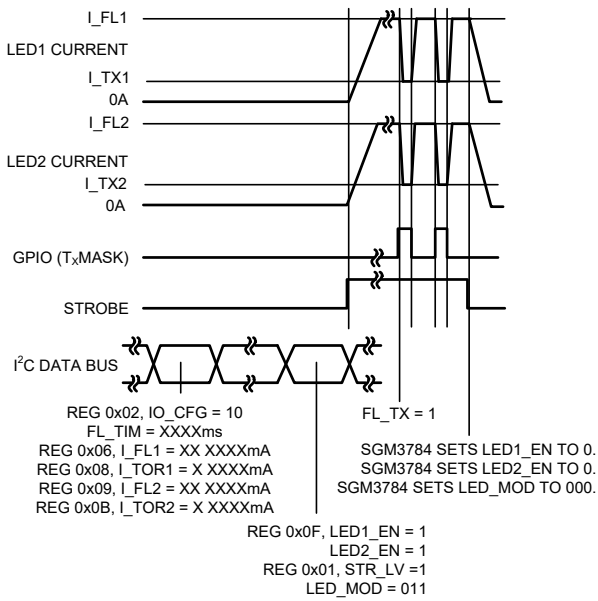


Figure 9. TxMASK Operation During Flash (Level-Sensitive) Mode

After a TxMASK event occurs, a flag is set in the fault information register (Register 0x0C, Bit 3). When the TxMASK signal goes low again, the LED current reverts to the full flash level in a controlled manner to avoid overshoots on the battery current.

Independent Trigger Modes

When the LED_MOD bits are set to 100 or 101, the SGM3784 allows for independent triggering of each LED at a current level between the configured flash currents and TxMASK currents. In independent trigger mode, the STROBE pin controls LED1, and the GPIO pin controls LED2 (see Figure 10).

- When the STROBE or GPIO pin goes high, the current produced at the LED1 or LED2 pin is at the level specified by the I_FL1 bits (Register 0x06) or the I_FL2 bits (Register 0x09), respectively.
- When the STROBE or GPIO pin goes low, the current produced at the LED1 or LED2 pin is at the level specified by the I_TX1 bits (Register 0x07) or the I_TX2 bits (Register 0x0A), respectively.

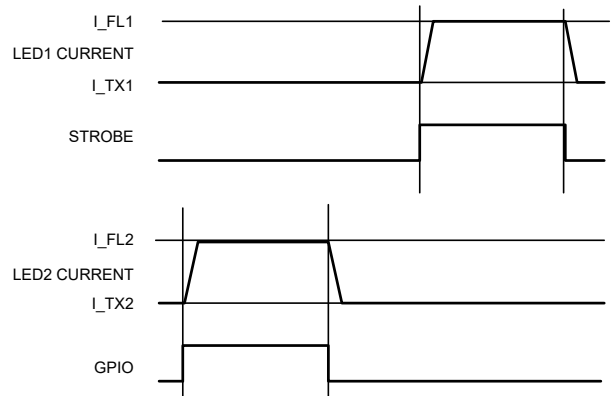


Figure 10. Independent Trigger Mode

When the LED_MOD bits are set to 100, the flash timer is used. If both LEDs are on for a combined time that is equal to the value specified by the FL_TIM bits (both outputs OR'ed), the SGM3784 sets both LED_ENx bits to 0 and sets LED_MOD to 000.

The independent trigger modes (LED_MOD bits set to 100 or 101) present a possible over-temperature risk; careful evaluation of their implementation must be performed.

THEORY OF OPERATION (continued)

Fixed 5V Output Mode

When the LED_MOD bits are set to 001, the SGM3784 allows VOUT to be regulated to 5V. In this mode, the total output current must be kept below 500mA. Enabling one or both LEDs allows low levels of current to the LEDs.

In fixed 5V output mode, the VOUT pin is connected to the SW node when the SGM3784 is not enabled. Do not connect VOUT directly to a positive external voltage source; doing so causes current to flow from VOUT to the battery. Changing the mode to standby (LED_MOD = 000) ends voltage regulation; VOUT returns to a value that is approximately the same as VIN.

Low Battery LED Current Foldback

As the battery discharges, the lower battery voltage results in higher peak currents through the battery ESR, which may cause early shutdown of other devices on the battery. The SGM3784 includes an optional low battery detection feature, which reduces the flash current to a value from 0mA to 1.1A when the battery voltage falls below a programmable level. The low battery current level can be set from 0mA to 1.1A using the I_VB_LO bits (Bits[5:0]) in Register 0x05.

To enable low battery detection and to specify the voltage at which this detection becomes active, set the V_VB_LO bits (Bits[2:0]) in Register 0x04 (see Table 2).

Table 2. VDD Level for Low Battery Detection

V_VB_LO BIT VALUE	V _{DD} LEVEL for LOW BATTERY DETECTION
000	Low battery detection disabled (default)
001	3.30V
010	3.35V
011	3.40V
100	3.45V
101	3.50V
110	3.55V
111	3.60V

If a low battery fault is detected within a programmed window of detection, the lower current is latched for the remainder of the flash. The window size is specified by the V_BATT_WINDOW bits (Bits[4:3]) in Register 0x04 (see Table 3).

Table 3. Low Battery Detection Window Size

V_BATT_WINDOW BIT VALUE	WINDOW SIZE (ms)
00	Window disabled; low battery detection is enabled for the entire flash period
01	1
10	2
11	5 (default)

By reducing the window size to the beginning of the flash only, the user can reduce the chance of partial exposure of the picture in the case that the image sensor is using a rolling scan. If a global scan is used, it is recommended that the low battery detection window be disabled, thereby providing low voltage protection throughout the flash time.

Battery Input DC Current Limit

The SGM3784 has an optional programmable input dc current limit that limits the maximum battery current used over all conditions. This feature allows higher LED currents to be used in a system with significant variation in LED forward voltage (V_F) and supply battery voltage without the risk of exceeding the current allocated to the flash. To enable the input dc current limit, set the IL_DC_EN bit (Bit 0) in Register 0x03. To set the input DC current limit, use the IL_DC bits (Bits[3:1]) in Register 0x03 (see Table 4).

Table 4. DC Current Limit

IL_DC BIT VALUE	DC CURRENT LIMIT (A)
000	1.00
001	1.25
010	1.50
011	1.75
100	2.00 (default)
101	2.25
110	2.50
111	2.75

THEORY OF OPERATION (continued)

During startup of the flash, if the battery current does not exceed the dc current limit, the LED1 and LED2 currents are set to the values of the I_FL1 and I_FL2 bits in Register 0x06 and Register 0x09, respectively.

If the battery current exceeds the programmed dc current limit on startup, the LED current does not increase further. The dc current limit flag is set in the fault information register (Bit 0 of Register 0x0C). The FL_I_FL1 bits in Register 0x0D and the FL_I_FL2 bits in Register 0x0E are set to the actual LED current values and are available for readback.

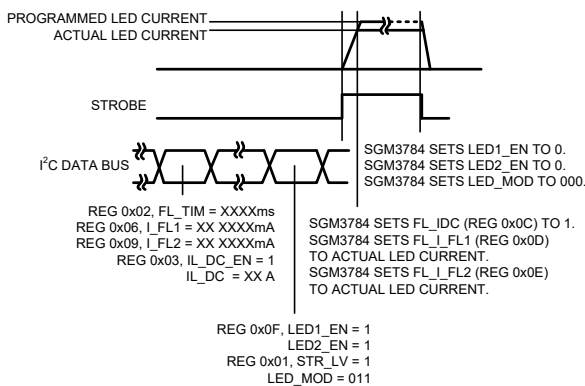


Figure 11. DC Current Limit Operation in a Low Battery, High LED V_F Case

The camera system shown in Figure 12 can adjust the image sensor settings based on the known reduced LED current for a low battery and a high V_F LED.

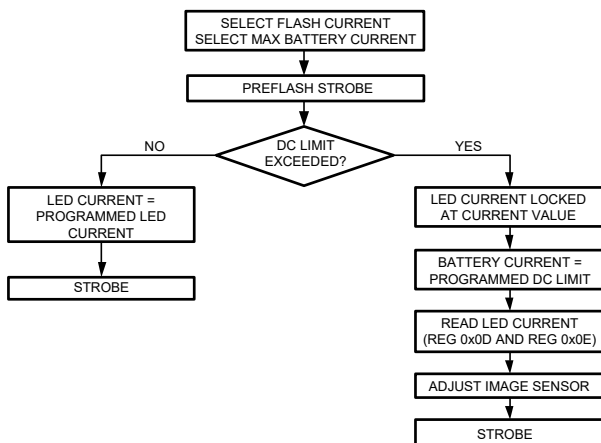


Figure 12. Use of the DC Current Limit in an Optimized Camera System

Fixed 5V Output Mode with Torch

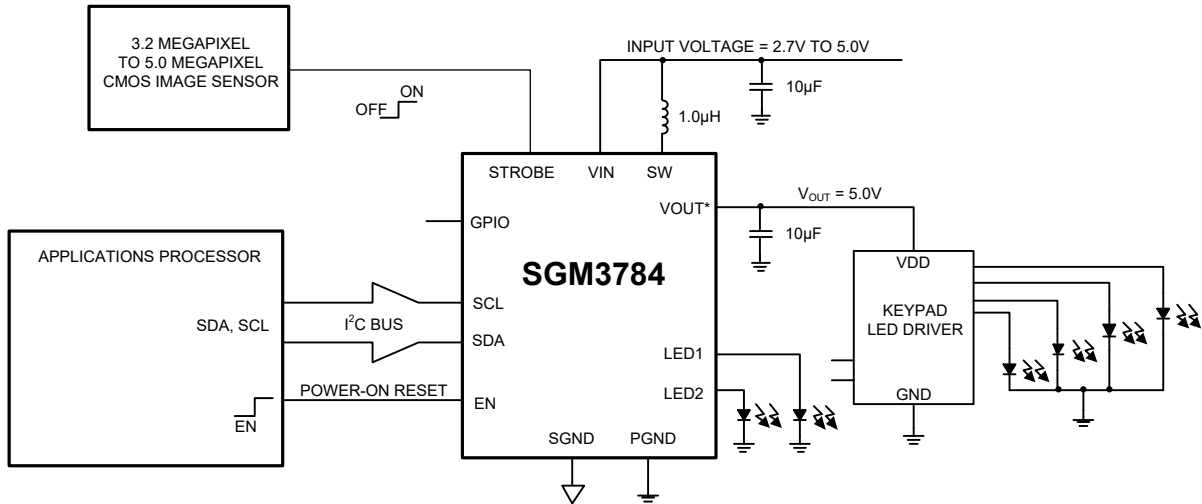
The SGM3784 can be used as a 5V boost converter for a keypad LED driver voltage or an audio voltage rail (see Figure 13 and Figure 14). In this mode, the device supplies up to 500mA with torch currents available on the LED outputs.

To enable 5V output voltage mode with torch currents,

1. Set the LED1_EN and LED2_EN bits in Register 0x0F to 0.
2. Enable the 5V output by setting the LED_MOD bits (Bits[2:0] in Register 0x01) to 110.
3. Enable the LED outputs by setting the LED1_EN and LED2_EN bits to 1.
4. If desired, set the torch/assist currents for the LEDs using Register 0x08 (for LED1) and Register 0x0B (for LED2). These currents can be toggled with the GPIO (torch) pin. If the LED is enabled and the GPIO (torch) pin is low, the LED outputs low levels of current.

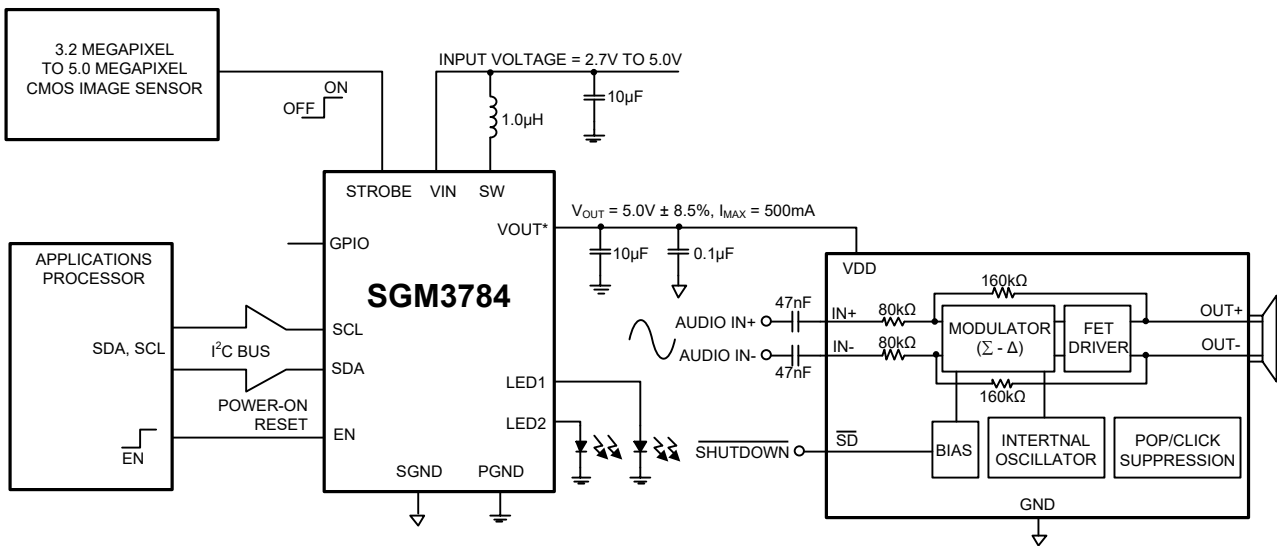
The VOUT pin is connected to the SW node when the SGM3784 is not enabled. Do not connect VOUT directly to a positive external voltage source; doing so causes current to flow from VOUT to the battery.

THEORY OF OPERATION (continued)



*THE VOUT Pin is connected to the SW node when the SGM3784 is not enabled. VOUT should not be connected directly to a positive external voltage source because this will cause current to flow from VOUT to the Battery.

Figure 13. SGM3784 Voltage Regulation Mode Keypad LED Driver Application



*THE VOUT Pin is connected to the SW node when the SGM3784 is not enabled. VOUT should not be connected directly to a positive external voltage source because this will cause current to flow from VOUT to the Battery.

Figure 14. SGM3784 Voltage Regulation Mode Class-D Audio Application

SAFETY FEATURES

For critical fault conditions, such as output over-voltage, flash timeout, LED output short circuit, and over-temperature conditions, the SGM3784 has built-in protection modes. If a critical fault occurs, the LED1_EN and LED2_EN bits in Register 0x0F are set to 0 and the driver shuts down. The appropriate fault bit is set in the fault information register (Register 0x0C). The processor can read the fault information register through the I²C interface to determine the nature of the fault condition. When the fault register is read, the fault bit is cleared.

If a noncritical event occurs, the LED driver continues to operate. Noncritical events include TxMASK event, dc current limit reached, or soft inductor current limit reached. The corresponding information bits are set in the fault information register (Register 0x0C) until the processor reads them.

Short-Circuit Fault

When the flash driver is disabled, the high-side current regulator disconnects the dc path between the battery and the LED, protecting the system from an LED short circuit. The LED1 and LED2 pins feature short-circuit protection that monitors the LED voltage when the LED driver is enabled. If the voltage on the LED1 or LED2 pin remains below the short-circuit detection threshold, a short circuit is detected, and Bit 6 of the fault information register (Register 0x0C) is set high. The SGM3784 remains disabled until the processor clears the fault register.

Over-Voltage Fault

The SGM3784 contains a comparator at the VOUT pin that monitors the voltage between VOUT and PGND. If the voltage exceeds 5.3V (typical), the SGM3784 shuts down. Bit 7 in the fault information register (Register 0x0C) is read back as high. The SGM3784 is disabled until the fault is cleared, ensuring protection against an open circuit, which would cause an over-voltage condition.

Dynamic Over-Voltage Protection Mode

Dynamic over-voltage protection (OVP) mode is a programmable feature that prevents the VOUT voltage from exceeding the OVP level while maintaining as much current as possible through the LEDs. Dynamic OVP mode prevents an over-voltage fault in the case of a much higher than expected LED forward voltage. If

the LED forward voltage is reduced due to a rise in LED temperature, the SGM3784 transitions out of dynamic OVP mode and regulates the LED at the programmed current level. To enable dynamic OVP mode, set Bit 6 of Register 0x03 high.

Timeout Fault

If hardware strobe mode is enabled and strobe is set to level-sensitive mode (Register 0x01, Bits[5:4] = 11) and if the STROBE pin remains high for longer than the programmed timeout period, the timeout fault bit (Register 0x0C, Bit 4) is read back as high.

The SGM3784 remains disabled until the processor clears the fault register. The timeout value is set using the FL_TIM bits (Bits[3:0]) in Register 0x02.

Over-Temperature Fault

If the junction temperature of the SGM3784 rises above 150°C, a thermal protection circuit shuts down the device. Bit 5 of the fault information register (Register 0x0C) is set high. The SGM3784 remains disabled until the processor clears the fault register.

Clearing Faults

The bits in the fault information register (Register 0x0C) are cleared automatically when the processor reads the fault register (provided that the faults no longer exist).

Current Limit

An internal switch limits battery current by ensuring that the peak inductor current does not exceed the limit programmed using Bits[7:6] in Register 0x01. By default, the soft inductor peak current limit mode is disabled (Register 0x03, Bit 7 = 1).

When the soft inductor peak current limit is disabled and the peak inductor current exceeds the limit, Bit 1 of the fault information register (Register 0x0C) is set high. The SGM3784 shuts down and remains disabled until the processor clears the fault register.

When the soft inductor peak current limit is enabled (Register 0x03, Bit 7 = 0) and the peak inductor current reaches the limit, Bit 1 of the fault information register (Register 0x0C) is set high. The inductor and LED current cannot increase further, but the SGM3784 continues to operate.

SAFETY FEATURES (continued)

Soft-Start

The SGM3784 uses a soft start that controls the rate of increase of battery current at startup by digitally controlling the output current ramp. The maximum soft start time is 0.6ms.

Reset Using the Enable (EN) Pin

A low-to-high transition on the EN pin resets all registers to their default values. Bringing EN low reduces the I_Q to 0.2μA (typical).

Input Under-Voltage Lockout

The SGM3784 includes a battery under-voltage lockout circuit. During fixed 5V output or LED operation, if the battery voltage falls below the input UVLO threshold (2.3V typical), the SGM3784 shuts down. A power-on reset circuit resets the registers to their default values when the voltage rises above the UVLO rising threshold.

I²C INTERFACE

The SGM3784 includes an I²C-compatible serial interface for control of the LED currents, as well as for readback of system status registers. The I²C chip address is 0x30 (0x60 in write mode and 0x61 in read mode). Additional I²C addresses are available on request.

Figure 15 shows the I²C write sequence for a single register. The sub-address byte selects the register that is written to. The SGM3784 sends an acknowledgment to the master after the 8-bit data byte is written. Figure 16 shows the I²C read sequence for a single register.

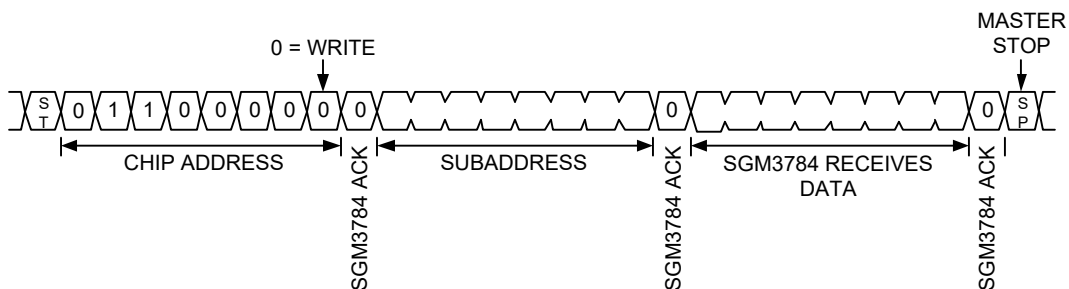


Figure 15. I²C Write Sequence for a Single Register

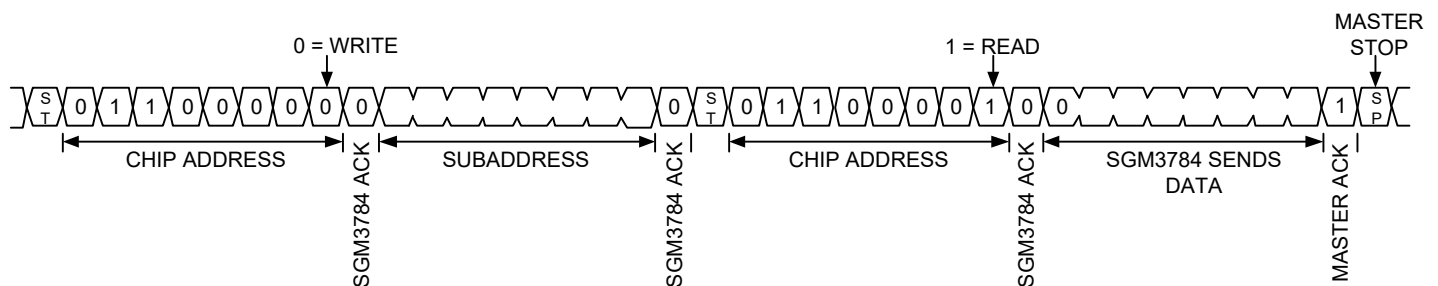


Figure 16. I²C Read Sequence for a Single Register

For information about the registers and descriptions of all register bits, see the Register Map section.

REGISTER MAP

The highest bit number (7) represents the most significant bit; the lowest bit number (0) represents the least significant bit.

Table 5. Register Map

ADDRESS	REGISTER NAME	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0
0x00	Design Information	DEVICE_ID				REV_ID			
0x01	Output Mode	IL_PEAK		STR_LV	STR_MOD	STR_POL	LED_MOD		
0x02	GPIO and Timer	LED_SD	TEST_SR	IO_CFG		FL_TIM			
0x03	Additional Features	CL_SOFT	DYN_OVP	SW_LO	FREQ_FB	IL_DC		IL_DC_EN	
0x04	Low Battery Mode Enable	Reserved			V_BATT_WINDOW		V_VB_LO		
0x05	Low Battery Mode Current	Reserved			I_VB_LO				
0x06	LED1 Flash Current	Reserved			I_FL1				
0x07	LED1 TxMASK Current	Reserved			I_TX1				
0x08	LED1 Torch/ Assist Current	Reserved			I_TOR1				
0x09	LED2 Flash Current	Reserved			I_FL2				
0x0A	LED2 TxMASK Current	Reserved			I_TX2				
0x0B	LED2 Torch/ Assist Current	Reserved			I_TOR2				
0x0C	Fault Information	FL_OVP	FL_SC	FL_OT	FL_TO	FL_TX	FL_VB_LO	FL_IL	FL_IDC
0x0D	LED1 Flash Current Fault Readback	Reserved			FL_I_FL1				
0x0E	LED2 flash Current Fault Readback	Reserved			FL_I_FL2				
0x0F	LED Enable Mode	Reserved						LED2_EN	LED1_EN

Register Details

Table 6. Design Information Register (Register 0x00)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:3]	DEVICE_ID	R	Device ID for the SGM3784 (00011).
[2:0]	REV_ID	R	Revision ID.

Table 7. Output Mode Register (Register 0x01)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:6]	IL_PEAK	R/W	These bits set the inductor peak current limit. 00 = 2.25A. 01 = 2.75A. 10 = 3.25A (default). 11 = 3.5A.
5	STR_LV	R/W	This bit sets the sensitivity for the STROBE pin. 0 = edge sensitive. 1 = level sensitive (default).
4	STR_MOD	R/W	This bit sets the strobe mode. 0 = software strobe mode; software flash occurs when the output is enabled in flash mode. 1 = hardware strobe mode; the STROBE pin must go high for flash (default).
3	STR_POL	R/W	This bit sets the polarity of the STROBE pin. 0 = active low. 1 = active high (default).
[2:0]	LED_MOD	R/W	These bits set the LED output mode. 000 = standby mode (default). 001 = fixed 5V output mode. 010 = assist light mode. 011 = flash mode. 100 = independent trigger mode with timeout enabled. 101 = independent trigger mode with timeout disabled. 110 = fixed 5V output mode with torch mode (total output current must be below 500mA). 111 = reserved.

REGISTER MAP (continued)**Table 8. GPIO and Timer Register (Register 0x02)**

BITS	BIT NAME	ACCESS	DESCRIPTION
7	LED_SD	R/W	This bit configures the shutdown function for LED1 and LED2. 0 = enter shutdown after LED1 or LED2 flash or torch ends (default). 1 = do not enter shutdown after LED1 or LED2 flash or torch ends.
6	TEST_SR	R/W	Test mode only. This bit must be set to its default value, 1. Do not set this bit to 0.
[5:4]	IO_CFG	R/W	These bits configure the GPIO pin. 00 = high impedance (default). 01 = torch mode. 10 = TxMASK operation mode. 11 = torch mode without the 10ms deglitch filter.
[3:0]	FL_TIM	R/W	These bits set the flash timer value. 0000 = 100ms. 0001 = 200ms. ... 0100 = 500ms. ... 0110 = 700ms. ... 1001 = 1000ms. ... 1100 = 1300ms. ... 1111 = 1600ms (default).

Table 9. Additional Features Register (Register 0x03)

BITS	BIT NAME	ACCESS	DESCRIPTION
7	CL_SOFT	R/W	This bit enables or disables the soft inductor peak current limit. 0 = enable soft inductor peak current limit. 1 = disable soft inductor peak current limit (default). The SGM3784 is disabled when the inductor peak current limit is reached.
6	DYN_OVP	R/W	This bit enables or disables dynamic OVP. 0 = disable dynamic OVP (default). 1 = enable dynamic OVP.
5	SW_LO	R/W	This bit sets the switching frequency. 0 = 3MHz (default). 1 = 1.6MHz.
4	FREQ_FB	Reserved	
[3:1]	IL_DC	R/W	These bits set the input dc current limit. (Bit 0 must be set to 1.) 000 = 1.0A. 001 = 1.25A. 010 = 1.5A. 011 = 1.75A. 100 = 2.0A (default). 101 = 2.25A. 110 = 2.5A. 111 = 2.75A.
0	IL_DC_EN	R/W	This bit enables or disables the input dc current limit function. 0 = disable input dc current limit (default). 1 = enable input dc current limit.

REGISTER MAP (continued)**Table 10. Low Battery Mode Enable Register (Register 0x04)**

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:5]	Reserved	R/W	Reserved.
[4:3]	V_BATT_WINDOW	R/W	These bits set the window size for low battery detection mode. 00 = window disabled; low battery detection is enabled for the entire flash period. 01 = window enabled for 1ms. 10 = window enabled for 2ms. 11 = window enabled for 5ms (default).
[2:0]	V_VB_LO	R/W	These bits enable or disable low battery detection and set the battery voltage level at which the low battery detection function is enabled. 000 = low battery detection disabled (default). 001 = low battery detection enabled at 3.3V. 010 = low battery detection enabled at 3.35V. 011 = low battery detection enabled at 3.4V. 100 = low battery detection enabled at 3.45V. 101 = low battery detection enabled at 3.5V. 110 = low battery detection enabled at 3.55V. 111 = low battery detection enabled at 3.6V.

Table 11. Low Battery Mode Current Register (Register 0x05)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:6]	Reserved	R/W	Reserved.
[5:0]	I_VB_LO	R/W	These bits set the flash current value for the low battery voltage setting. The current setting is equal to the value of these six bits multiplied by 18.7mA nominally ($I_{VB_LO} \times 18.7$). 00 0000 = 0mA. 00 0001 = 18.7mA. ... 01 0000 = 299.2mA (default). ... 10 1000 = 748mA. ... 11 1100 = 1122mA. ... 11 1111 = 1122mA

Table 12. LED1 Flash Current Register (Register 0x06)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:6]	Reserved	R/W	Reserved.
[5:0]	I_FL1	R/W	These bits set the flash current value for LED1. The current setting is equal to the value of these six bits multiplied by 18.7mA nominally ($I_{FL1} \times 18.7$ mA). 00 0000 = 0mA. 00 0001 = 18.7mA. ... 01 0000 = 299.2mA ... 10 1000 = 748mA (default). ... 11 1100 = 1122mA. ... 11 1111 = 1122mA

REGISTER MAP (continued)

Table 13. LED1 TxMASK Current Register (Register 0x07)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:6]	Reserved	R/W	Reserved.
[5:0]	I_TX1	R/W	These bits set the TxMASK current value for LED1. The current setting is equal to the value of these six bits multiplied by 18.7mA nominally ($I_{TX1} \times 18.7$). 00 0000 = 0mA. 00 0001 = 18.7mA. ... 01 0000 = 299.2mA ... 10 1000 = 748mA (default). ... 11 1100 = 1122mA. ... 11 1111 = 1122mA

Table 14. LED1 Torch/Assist Current Register (Register 0x08)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:5]	Reserved	R/W	Reserved.
[4:0]	I_TOR1	R/W	These bits set the torch/assist current value for LED1. The current setting is equal to the value of these five bits multiplied by 18.7mA nominally ($I_{TOR1} \times 18.7$). 0 0000 = 0mA. ... 0 0100 = 74.8mA (default). ... 0 1000 = 149.6mA. ... 0 1100 = 224.4mA. ... 1 0000 = 299.2mA. ... 1 1111 = 299.2mA.

Table 15. LED2 Flash Current Register (Register 0x09)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:6]	Reserved	R/W	Reserved.
[5:0]	I_FL2	R/W	These bits set the flash current value for LED2. The current setting is equal to the value of these six bits multiplied by 18.7mA nominally ($I_{FL2} \times 18.7$). 00 0000 = 0mA. 00 0001 = 18.7mA. ... 01 0000 = 299.2mA ... 10 1000 = 748mA (default). ... 11 1100 = 1122mA. ... 11 1111 = 1122mA

REGISTER MAP (continued)

Table 16. LED2 TxMASK Current Register (Register 0x0A)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:6]	Reserved	R/W	Reserved.
[5:0]	I_TX2	R/W	These bits set the TxMASK current value for LED2. The current setting is equal to the value of these six bits multiplied by 18.7mA nominally ($I_{TX2} \times 18.7$). 00 0000 = 0mA. 00 0001 = 18.7mA. ... 01 0000 = 299.2mA ... 10 1000 = 748mA (default). ... 11 1100 = 1122mA. ... 11 1111 = 1122mA

Table 17. LED2 Torch/Assist Current Register (Register 0x0B)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:5]	Reserved	R/W	Reserved.
[4:0]	I_TOR2	R/W	These bits set the torch/assist current value for LED2. The current setting is equal to the value of these five bits multiplied by 18.7mA nominally ($I_{TOR2} \times 18.7$). 0 0000 = 0mA. ... 0 0100 = 74.8mA (default). ... 0 1000 = 149.6mA. ... 0 1100 = 224.4mA. ... 1 0000 = 299.2mA. ... 1 1111 = 299.2mA.

Table 18. Fault Information Register (Register 0x0C)

BITS	BIT NAME	ACCESS	DESCRIPTION
7	FL_OVP	R	0 = no over-voltage fault (default). 1 = over-voltage fault.
6	FL_SC	R	0 = no short-circuit fault (default). 1 = short-circuit fault.
5	FL_OT	R	0 = no over-temperature fault (default). 1 = over-temperature fault.
4	FL_TO	R	0 = no timeout fault (default). 1 = timeout fault.
3	FL_TX	R	0 = no TxMASK operation mode during last flash (default). 1 = TxMASK operation mode occurred during last flash.
2	FL_VB_LO	R	Low battery detection threshold status; low battery detection must be enabled in Register 0x04. 0 = V_{DD} is greater than the configured low battery threshold (default). 1 = V_{DD} is less than the configured low battery threshold.
1	FL_IL	R	0 = no inductor peak current limit fault (default). 1 = inductor peak current limit fault.
0	FL_IDC	R	DC current limit threshold status; dc current limit must be enabled in Register 0x03. 0 = dc current limit not reached (default). 1 = dc current limit reached.

REGISTER MAP (continued)

Table 19. LED1 Flash Current Fault Readback Register (Register 0x0D)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:6]	Reserved	R	Reserved.
[5:0]	FL_I_FL1	R	These bits contain the flash current value for LED1 when the dc current limit fault occurs. The current setting is equal to the value of these six bits multiplied by 18.7mA nominally (FL_I_FL1 × 18.7). 00 0000 = 0mA. 00 0001 = 18.7mA. ... 01 0000 = 299.2mA ... 10 1000 = 748mA. ... 11 1100 = 1122mA.

Table 20. LED2 Flash Current Fault Readback Register (Register 0x0E)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:6]	Reserved	R	Reserved.
[5:0]	FL_I_FL2	R	These bits contain the flash current value for LED2 when the dc current limit fault occurs. The current setting is equal to the value of these six bits multiplied by 18.7mA nominally (FL_I_FL2 × 18.7). 00 0000 = 0mA. 00 0001 = 18.7mA. ... 01 0000 = 299.2mA ... 10 1000 = 748mA. ... 11 1100 = 1122mA.

Table 21. LED Enable Mode Register (Register 0x0F)

BITS	BIT NAME	ACCESS	DESCRIPTION
[7:2]	Reserved	R/W	Reserved.
1	LED2_EN	R/W	This bit enables or disables the LED2 output. 0 = disable LED2 output (default). 1 = enable LED2 output. To enable both channels at once, set both LED2_EN and LED1_EN to 0 and then set both bits to 1 in the same I ² C write command. If LED1 is already enabled and the user tries to set the LED2_EN bit to 1, this write is ignored.
0	LED1_EN	R/W	This bit enables or disables the LED1 output. 0 = disable LED1 output (default). 1 = enable LED1 output. To enable both channels at once, set both LED1_EN and LED2_EN to 0 and then set both bits to 1 in the same I ² C write command. If LED2 is already enabled and the user tries to set the LED1_EN bit to 1, this write is ignored.

APPLICATION INFORMATION

Selecting the Inductor

The SGM3784 boost converter increases the battery voltage to allow driving of two LEDs when the forward voltage of the LEDs is higher than the battery voltage minus 2× the current source headroom voltage. This allows the converter to regulate the LED current over the entire battery voltage range and with a wide variation of LED forward voltages.

The inductor saturation current should be greater than the sum of the dc input current and half the inductor ripple current. A reduction in the effective inductance due to saturation increases the inductor ripple current. Table 22 provides a list of suggested inductors.

Table 22. Suggested Inductors

VENDOR	VALUE (μH)	PART NO.	DCR (mΩ)	I _{SAT} (A)	DIMENSIONS L × W × H (mm)
Toko	1.0	FDSD0312	43	4.5	3.0 × 3.0 × 1.2
Toko	1.0	DFE2520	50	3.4	2.5 × 2.0 × 1.0
Coilcraft	1.0	XFL3010	43	2.4	3.0 × 3.0 × 1.0
Murata	1.0	LQM32P_G0	48	3	3.2 × 2.5 × 1.0
FDK	1.0	MIP3226D	40	3	3.2 × 2.6 × 1.0

Selecting the Input Capacitor

The SGM3784 requires an input bypass capacitor to supply transient currents while maintaining constant input and output voltages. The input capacitor carries the input ripple current, allowing the input power source to supply only the dc current. Increased input capacitance reduces the amplitude of the switching frequency ripple on the battery. Due to the dc bias characteristics of ceramic capacitors, the recommended capacitor is a 10.0μF, 6.3V, X5R/X7R ceramic capacitor.

Higher input capacitor values help to reduce the input voltage ripple and improve transient response.

To minimize supply noise, place the input capacitor as close to the VIN pin of the SGM3784 as possible. A low ESR capacitor is required. Table 23 provides a list of suggested input and output capacitors.

Table 23. Suggested Input and Output Capacitors

VENDOR	VALUE	PART NO.	DIMENSIONS L × W × H (mm)
Murata	10μF, 6.3V	GRM188R60J106ME47	1.6 × 0.8 × 0.8
TDK	10μF, 6.3V	C1608JB0J106K	1.6 × 0.8 × 0.8
Taiyo Yuden	10μF, 6.3V	JMK107BJ106MA	1.6 × 0.8 × 0.8

Selecting the Output Capacitor

The output capacitor maintains the output voltage and supplies the LED current during the on period of the N-FET power switch. It also stabilizes the loop. The recommended capacitor is a 10.0μF, 6.3V, X5R/X7R ceramic capacitor (see Table 23).

Note that dc bias characterization data is available from capacitor manufacturers and should be taken into account when selecting input and output capacitors. Capacitors of 6.3V or 10V are best for most designs.

Higher output capacitor values reduce the output voltage ripple and improve load transient response. When selecting an output capacitor value, it is also important to account for the loss of capacitance due to output voltage dc bias.

Ceramic capacitors have a variety of dielectrics, each with different behavior over temperature and applied voltage. Capacitors must have a dielectric that ensures the minimum capacitance over the necessary temperature range and dc bias conditions. X5R or X7R dielectrics with a voltage rating of 6.3V or 10V are recommended for best performance. Y5V and Z5U dielectrics are not recommended for use with any dc-to-dc converter because of their poor temperature and dc bias characteristics.

The worst-case capacitance accounting for capacitor variation over temperature, component tolerance, and voltage is calculated using the following equation:

$$C_{EFF} = C_{OUT} \times (1 - TEMPCO) \times (1 - TOL)$$

Where:

C_{EFF} is the effective capacitance at the operating voltage.

TEMPCO is the worst-case capacitor temperature coefficient.

TOL is the worst-case component tolerance.

APPLICATION INFORMATION (continued)

For example, a 10µF, X5R capacitor has the following characteristics:

TEMPCO from -40°C to +85°C is 15%.

TOL is 10%.

C_{OUT} at V_{OUT (MAX)} = 5V is 3µF.

Substituting these values in the equation yields

$$C_{EFF} = 3\mu F \times (1 - 0.15) \times (1 - 0.1) = 2.3\mu F$$

The effective capacitance needed for stability, which includes temperature and dc bias effects, is 3.0µF.

PCB Layout

Poor layout can affect performance, causing electromagnetic interference (EMI) and electromagnetic compatibility (EMC) problems, ground bounce, and power losses. Poor layout can also affect regulation and stability. When laying out the printed circuit board, the following guidelines should be used to

ensure proper operation of the SGM3784. Check the following in your layout:

- Place the inductor, input capacitor, and output capacitor close to the IC using short tracks. These components carry high switching frequencies and large currents.
- Use as wide a trace as possible between the inductor and the SW pin. The easiest path for this trace is through the center of the output capacitor.
- Route the LED1/LED2 path away from the inductor and SW node to minimize noise and magnetic interference.
- Maximize the size of ground metal on the component side of the board to help with thermal dissipation.
- Use a ground plane with two or three vias connecting to the component side ground near the output capacitor to reduce noise interference on sensitive circuit nodes.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

SEPTEMBER 2017 – REV.A.1 to REV.A.2

Updated Electrical Characteristics	4
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MAY 2017 – REV.A to REV.A.1

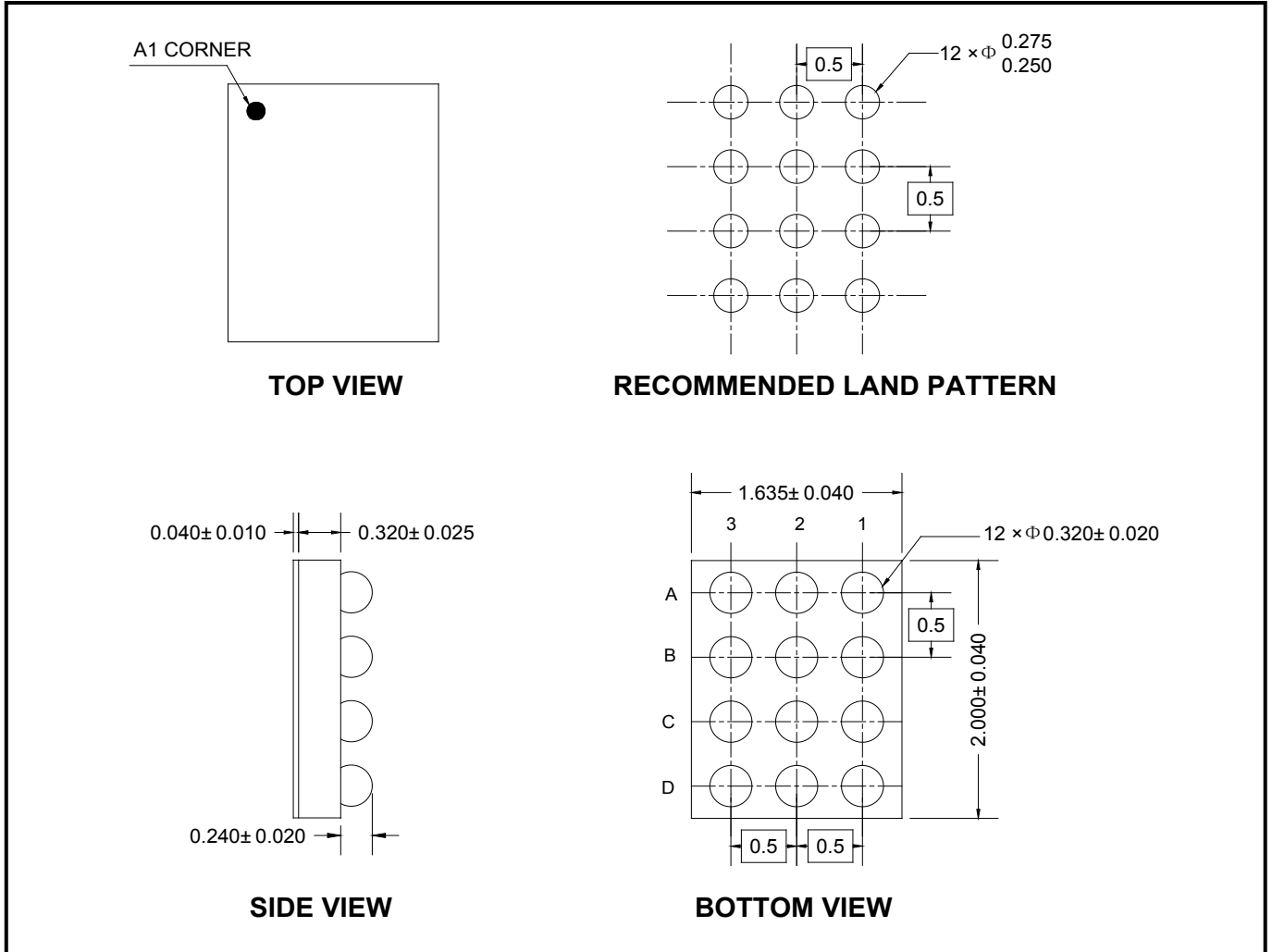
Updated Packing Option.....	2
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Changes from Original (FEBRUARY 2016) to REV.A

Changed from product preview to production data.....	All
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PACKAGE OUTLINE DIMENSIONS

WLCSP-2x1.6-12B



NOTE: All linear dimensions are in millimeters.

PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
WLCSP-2×1.6-12B	7"	9.2	1.80	2.20	0.80	4.0	4.0	2.0	8.0	Q1

000001

PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18

DD0002

单击下面可查看定价，库存，交付和生命周期等信息

[>>SGMICRO\(圣邦微电子\)](#)